Emma Boya Peng

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Education

Stanford University

Stanford, CA

M.S. Candidate, Computer Science (AI). GPA: 4.07/4.0

Sept 2015 - Present

The University of Hong Kong

Hong Kong

B.Eng. Computer Science. GPA: 3.81/4.3

Sept 2012 - June 2015

University of California, San Diego

San Diego, CA

Exchange Student, Computer Science. GPA: 4.0/4.0

Sept 2013 - Dec 2013

Publications

Towards Viewpoint Invariant 3D Human Pose Estimation

ECCV

Albert Haque, Boya Peng, Zelun Luo, Alexandre Alahi, Serena Yeung, Li Fei-Fei

2016

Vision-Based Hand Hygiene Monitoring in Hospital

NIPS Workshop

Serena Yeung, Alexandre Alahi, Zelun Luo, Boya Peng, Albert Haque, Li Fei-Fei

. 2016

Experience

A9.com

Palo Alto, CA

Software Development Intern, Product Search

June 2016 - Sept 2016

- Developed a deep sequence to sequence neural language model to generate relevant queries for Amazon products using TensorFlow.

Stanford University

Stanford, CA

Research Assistant, Computer Vision Lab

Oct 2015 - June 2016

- DeepAnnotator: built an interactive video annotation web interface for building massive video datasets.
- Discriminatory Image Captioning: built an image captioning model that generates more descriptive captions by enforcing the alignments between images and generated captions while penalizing misaligned pairs.
- 3D Human Pose Estimation: proposed an approach that leverages a convolutional and recurrent network with a top-down error feedback mechanism to self-correct previous pose estimates in an end-to-end manner.

Qifun Network Co

Shenzhen, China

Machine Learning Intern

June 2015 - Aug 2015

- Developed machine learning frameworks using Spark for game telemetry data.
- Built a game log analysis tool for data processing.

The University of Hong Kong

Hong Kong

Research Assistant, Programming Languages Group

Feb 2015 - May 2015

- Developed a simple technique that allows non-trivial, but compositional interpretations of Domain Specific Languages to be expressed in a fully modular way using folds.

Honors and Awards

- o HKMA Information Technology Management Club Scholarship 2014-2015
- o Institute of Electrical and Electronics Engineers (Hong Kong Section) Prize 2013-2014
- Undergraduate Research Fellowship Program 2014
- o HKUWW Scholarship (Exchange Studies at University of California, San Diego), 2013-2014
- o Ho Fook's Prize in Engineering 2012-2013
- o Walter Brown Memorial Prize in Mathematics 2012-2013